



For Immediate Release

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**Taconic Introduces Low Loss Flexible Bondply
for Complex Rigid/Flex PWBs at Designcon 2016**

Santa Clara, CA, January 20-21, 2016 – At Designcon 2016, Taconic's Advanced Dielectric Division will announce *fastRise™ EZp* which promises advances in flexible circuit fabrication. FR-EZp is a low temperature curing, low loss flexible bondply designed to enable the manufacture of complex rigid/flex PWBs containing polyimide (DuPont™ Pyralux® AP/TK flexible circuit material), LCP or PTFE cores without excessive movement.

Based on ceramic, thermoset and a thermoplastic based film, *fastRise™ EZp* bonds well to Taconic's PTFE cores and is an ideal candidate to bond core materials where it is otherwise difficult to obtain good adhesion. Difficult-to-bond-to substrates such as Pyralux® AP, PEEK, LCP, flat planes of PTFE or hydrocarbon (synthetic rubber) can be well bonded with FR-EZp. Taconic's PTFE-rich TLY 5 and other non reinforced PTFE-rich substrates also bond well with FR-EZp.

fastRise™ EZp's low loss (FR-EZ22p = 0.0018 and FR-EZ33p = 0.0024 at 10 GHz) enables the design of flexible high speed cables and rigid RF/digital multilayers without the uncertainties and costs associated with the high temperature lamination of PTFE or LCP materials.

FR-EZp can be sequentially laminated, has better bonding capabilities with copper than other RF prepregs and will yield higher peel strengths in a foil lamination. The low DK of FR-EZp is advantageous in flex applications to reduce thickness while maintaining the same impedance. The low modulus of FR-EZp allows for more ductility in a thicker multilayer.

Pyralux® is a registered trademark of E.I. du Pont de Nemours and Company